

CLAIMS

1. A solid-state image pickup apparatus which incorporates a semiconductor substrate having an image pickup region including unit pixels disposed in a two-dimensional configuration and signal scanning sections for reading signals from the unit pixels in the image pickup region, the solid-state image pickup apparatus comprising:

10 a photoelectric conversion region having a first-conduction-type signal accumulating section formed at a position apart from an interface of the semiconductor substrate in a direction of a depth of the semiconductor substrate for a predetermined distance and arranged to accumulate signal charges obtained from 15 photoelectric conversion;

20 a gate electrode of a first-conduction-type MOS field effect transistor formed adjacent to the photoelectric conversion region and arranged to discharge a signal charge from the first-conduction-type signal accumulating section;

25 a first-conduction-type detecting node section serving as a drain region for receiving the signal charges from the photoelectric conversion region via the gate electrode; and

a barrier layer formed at least close to a lower part of the first-conduction-type detecting node section of the MOS field effect transistor, wherein

- 5 at least a part of the first-conduction-type signal accumulating section in a direction of a channel thereof extends to overlap the gate electrode in a direction in which signals are discharged,

modulation of the potential of the gate electrode is used to discharge signals from the first-conduction-type 10 signal accumulating section through the channel of the MOS field effect transistor, and

the first-conduction-type detecting node section is not located below the gate electrode but at an opposite side of the gate electrode.

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2. A solid-state image pickup apparatus according to claim 1, further comprising a diffusion-layer region which is formed in the interface of the semiconductor substrate above the first-conduction-type signal 20 accumulating section, which has a second-conduction-type opposite to the conduction type of the first-conduction-type signal accumulating section and which contains impurities at a concentration which is higher than the concentration of impurities contained in 25 the channel region of the first-conduction-type MOS field effect transistor.

3. A solid-state image pickup apparatus according
to claim 1, wherein a length of a portion of the
first-conduction-type signal accumulating section
5 extending to overlap the gate electrode in the direction
in which signals are discharged is shorter than 1/2 of a
length of the gate electrode of the first-conduction-type
MOS field effect transistor.

10 4. A solid-state image pickup apparatus according
to claim 2, wherein a length of a portion of the
first-conduction-type signal accumulating section
extending to overlap the gate electrode in the direction
in which signals are discharged is shorter than 1/2 of a
15 length of the gate electrode of the first-conduction-type
MOS field effect transistor.

5. A solid-state image pickup apparatus according
to claim 2, wherein a length of a portion of the
20 first-conduction-type signal accumulating section
extending to overlap the gate electrode in the direction
in which signals are discharged is longer than 1/2 of a
depth of a junction of the diffusion-layer region from
the interface of the semiconductor substrate.

6. A solid-state image pickup apparatus according to claim 1, wherein the first-conduction-type signal accumulating section has a first region formed below the gate electrode and a second region formed at a position
5 except for a position below the gate electrode, and a depth of the first-conduction-type signal accumulating section in the first region from the interface of the semiconductor substrate is smaller than a depth of the first-conduction-type signal accumulating section in the
10 second region.

7. A solid-state image pickup apparatus according to claim 2, wherein the first-conduction-type signal accumulating section has a first region formed below the gate electrode and a second region formed at a position
15 except for a position below the gate electrode, and a depth of the first-conduction-type signal accumulating section in the first region from the interface of the substrate is smaller than a depth of the
20 first-conduction-type signal accumulating section in the second region.

8. A solid-state image pickup apparatus according to claim 3, wherein the first-conduction-type signal accumulating section has a first region formed below the gate electrode and a second region formed at a portion
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except for a position below the gate electrode, and a
depth of the first-conduction-type signal accumulating
section in the first region from the interface of the
substrate is smaller than a depth of the
5 first-conduction-type signal accumulating section in the
second region.

9. A solid-state image pickup apparatus according
to claim 4, wherein the first-conduction-type signal
10 accumulating section has a first region formed below the
gate electrode and a second region formed at a position
except for a position below the gate electrode, and a
depth of the first-conduction-type signal accumulating
section in the first region from the interface of the
substrate is smaller than a depth of the
15 first-conduction-type signal accumulating section in the
second region.

10. A solid-state image pickup apparatus according
20 to claim 5, wherein the first-conduction-type signal
accumulating section has a first region formed below the
gate electrode and a second region formed at a position
except for a position below the gate electrode, and a
depth of the first-conduction-type signal accumulating
section in the first region from the interface of the
substrate is smaller than a depth of the
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first-conduction-type signal accumulating section in the second region.

11. A solid-state image pickup apparatus

5 incorporating a first-conduction-type well region formed on a semiconductor substrate, a photodiode section formed on the first-conduction-type well region and having a second-conduction-type region, a first-conduction-type surface layer formed on the second-conduction-type region
10 of the photodiode section, a second-conduction-type drain region formed in the first-conduction-type well region adjacent to the second-conduction-type region of the photodiode section, and a gate section of a reading transistor formed above the first-conduction-type well
15 region at a position between the second-conduction-type drain region and the second-conduction-type region of the photodiode section, the solid-state image pickup apparatus comprising:

a second-conduction-type barrier well formed by an
20 offset which extends from a deep portion in the second-conduction-type drain region toward the second-conduction-type region of the photodiode section, whose concentration is higher than a concentration of a first-conduction-type well layer, the
25 second-conduction-type barrier well being formed at last

at a lower part of the second-conduction-type drain region; and

a second-conduction-type and high-concentration channel formation layer located at a position more 5 adjacent to a surface layer than a position of the second-conduction-type barrier well, and also provided toward an end of the gate section.

12. A solid-state image pickup apparatus according 10 to claim 11, wherein the second-conduction-type and high-concentration channel formation layer is formed to extend over the second-conduction-type region of the photodiode section at a position between the first-conduction-type surface layer and a position below the gate section.

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13. A solid-state image pickup apparatus according to claim 11, further comprising a second-conduction-type channel formation layer formed on the second-conduction-type barrier well at a position 20 adjacent to both of the photodiode section and the second-conduction-type drain region.

14. A solid-state image pickup apparatus according to claim 11, wherein a first-conduction-type barrier well 25 having a concentration higher than the concentration in

the first-conduction-type well layer is formed in place
of the second-conduction-type barrier well.

15. A solid-type image pickup apparatus
5 incorporating a photodiode region, which has a shield
layer for preventing surface recombination and which is
formed into a surface shield structure, and a reading
gate electrode for reading charges in the photodiode
region, the solid-state image pickup apparatus comprising:

10 an impurity region formed at least between the
reading gate electrode and the shield layer, having a
depth which is different from a depth of the photodiode
region;

a drain region to which a charge inside the
15 photodiode region is transferred from the reading gate
electrode; and

a barrier layer formed close to at least a lower
part of the drain region, having a concentration higher
than a concentration of a semiconductor substrate.

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16. A solid-state image pickup apparatus according
to claim 15, wherein the shield layer is formed apart
from the reading gate electrode.

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17. A solid-state image pickup apparatus according
to claim 15, wherein the impurity region shares at least

a part of the photodiode region and contains an end of
the photodiode region.

18. A solid-state image pickup apparatus according
5 to claim 15, wherein the impurity region has a part which
reaches a lower portion of the reading gate electrode.

19. A solid-state image pickup apparatus according
to claim 15, wherein the impurity region has a
10 concentration higher than a concentration in the
photodiode region.